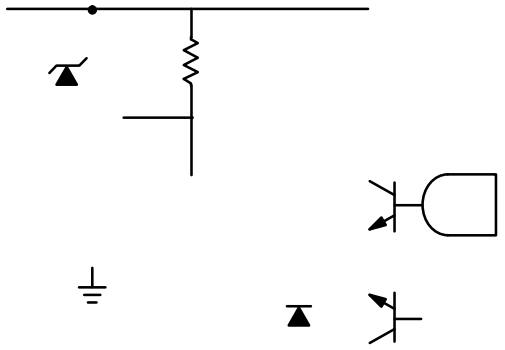
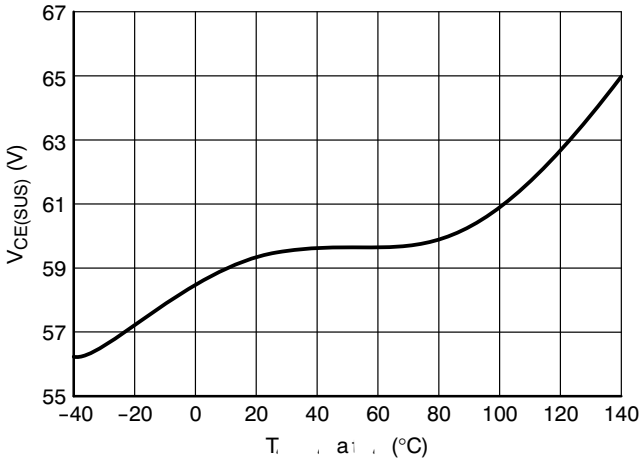
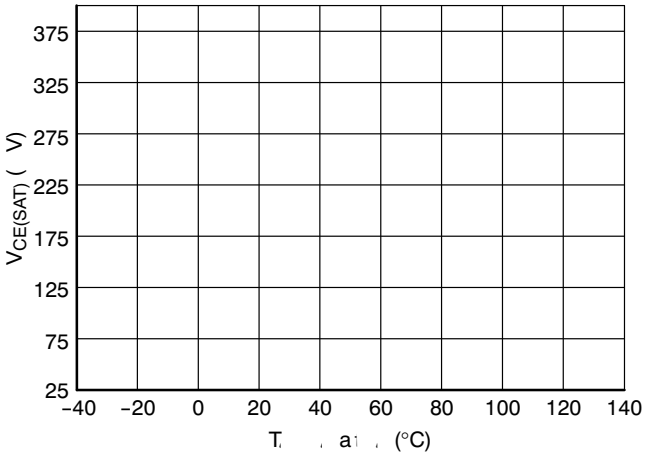
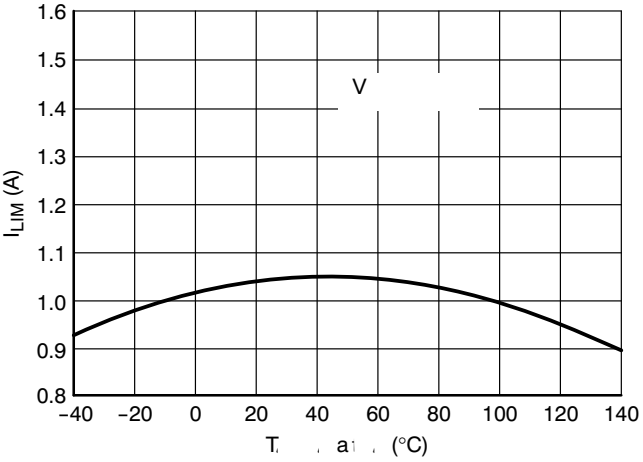
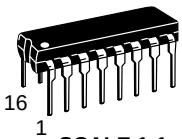


#		
1	OUTA	D A O 1
2	CLAMPAB	D Ca D Aa D B
3	OUTB	D B O 1
4	GND	G 1
5	GND	G 1
6	OUTC	D C O 1
7	CLAMPCD	D Ca D Ca D D
8	OUTD	D D O 1
9	IND	D D I 1
10	INC	D C I 1
11	V_{CC}	5.0 V I 1 S V a
12	GND	G 1
13	GND	G 1
14	[redacted]	[redacted]


67
65
63
61
59
57
55
$V_{CE(SUS)}$ (V)
−40 −20 0 20 40 60 80 100 120 140
T (°C)


375
325
275
225
175
125
75
25
$V_{CE(SAT)}$ (V)
−40 −20 0 20 40 60 80 100 120 140
T (°C)

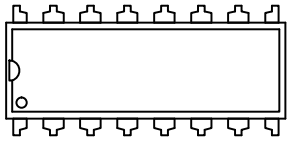

1.6
1.5
1.4
1.3
1.2
1.1
1.0
0.9
0.8
I_{LIM} (A)
V
−40 −20 0 20 40 60 80 100 120 140
T (°C)

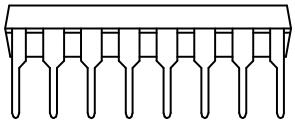


SCALE 1:1

PDIP−16
CASE 648−08
ISSUE V

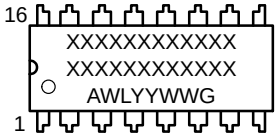
DATE 22 APR 2015





STYLE 1:

GENERIC
MARKING DIAGRAM*



XXXXX	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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